Application No.: TBA 3 Docket No.: 8733.311.10-US

## IN THE CLAIMS

1-12 (Canceled).

13. (Original) A method of cleaning a substrate of a liquid crystal display panel comprising: providing a first cleaning module on a substrate, said substrate having upper and lower surfaces;

providing a side-cleaning module on a side surface of the substrate;

removing foreign substances on a side surface of the substrate using the side-cleaning module; and

removing foreign substances on the upper and lower surface of the substrate using the cleaning module.

- 14. (Original) The method of claim 13, wherein the side-cleaning module is rotatable.
- 15. (Original) The method of claim 14, wherein the side-cleaning module extends partially along the side surface of the substrate.
- 16. (Original) The method of claim 13, wherein the first cleaning module is rotatable.
- 17. (Original) The method of claim 13, wherein the first cleaning module includes upper and lower cleaning brushes.
- 18. (Original) The method of claim 16, wherein the upper and lower cleaning brushes are arranged at the upper and lower surfaces of the substrate, respectively.
- 19. (Original) The method of claim 13, further comprising cleaning the side surface of the substrate using a water jet device.

20. (Original) The method of claim 18, wherein the water jet device generates ultrasonic waves.

- 21. (Original) The method of claim 18, wherein the cleaning step includes jetting water onto the side surface of the substrate at a high pressure.
- 22. (Original) The method of claim 21, wherein the water includes de-ionized water.
- 23. (Original) A method of cleaning a substrate of a liquid crystal display panel comprising: providing a cleaning module at a substrate, said substrate having upper and lower surfaces;

providing a side-cleaning module arranged at a side surface of the substrate; removing foreign substances on a side surface of the substrate using the side-cleaning module;

removing foreign substances on the upper and lower surface of the substrate using the cleaning module; and

cleaning the side surface of the substrate using a water jet device.

- 24. (Original) The method of claim 22, wherein the water jet device causes vibration on the side surface of the substrate.
- 25. (Original) The method of claim 23, wherein the vibration is generated by ultrasonic waves.
- 26. (Original) The method in claim 23, wherein the cleaning step includes jetting water onto the side surface of the substrate at a high pressure.
- 27. (Original) The method of claim 26, wherein the water includes de-ionized water.